

INTERNATIONAL STANDARD

**Semiconductor devices -
Part 5-18: Optoelectronic devices - Light emitting diodes - Test method of the
macro photoluminescence for epitaxial wafers of micro light emitting diodes**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

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The text of this International Standard is based on the following documents:

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Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

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- reconfirmed,
- withdrawn, or
- revised.

1 Scope

This part of IEC 60747-5 specifies the measuring methods of macro photoluminescence (PL) for red, green, and blue epitaxial wafers of micro light emitting diodes (LEDs) prior to chip fabrication processes. Wafer sizes being considered are 4 in, 6 in, and 8 in in diameter.

2 Normative references

There are no normative references in this document.

Bibliography

- [1] I. Choi, S. Min, J.-I. Shim, and D.-S. Shin, *IET Optoelectron.* 17, 32 (2023).
 - [2] CIE 250:2022, *Spectroradiometric measurement of optical radiation sources*
 - [3] IEC 60050-731:1991, *International Electrotechnical Vocabulary (IEV) - Part 731: Optical fibre communication* (available at www.electropedia.org)
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